

ABSTRACT OF THE DISCLOSURE

The present invention relates a manufacturing method of ceramic device either comprising the steps of forming by layer accumulation of a lower electrode, a piezoelectric/electrostrictive layer, and an upper electrode on a substrate using a mixture of photosensitive resin and metal or piezoelectric/electrostrictive ceramic; and patterning by light exposure at a single time, or repeating the step of patterning by light exposure after formation for layer by layer, or a manufacturing method of ceramic device either comprising the steps of forming by layer accumulation of a piezoelectric/electrostrictive layer and an upper electrode on a metal substrate using a mixture of photosensitive resin and metal or piezoelectric/electrostrictive ceramic; and patterning by light exposure at a single time, or repeating the step of patterning by light exposure after formation for layer by layer, thereby ceramic device of high shape ratio can be produced and precision degree is very high so as to produce a ceramic device very precise in arrangement between layers or with infrastructure so that another effect may be made to systematically prevent the short between upper and lower electrodes.